

Materials Declaration

Package	LCC
Body Size	
Lead Count	8
Option	e4 with exemption

Ceramic Base			
Item	% of Compound	Weight (g)	PPM
Alumina	91.3	9.70 E-02	614430
Chromium oxide	3.9	4.09 E-03	25904
Silicon dioxide	3.6	3.80 E-03	24087
Titanium dioxide	0.99	1.05 E-03	6661
Molybdenum	0.26	2.76 E-04	1749
Subtotal		1.06 E-01	672832

Terminals			
Item	% of Terminal	Weight (g)	PPM
Tungsten	83.6	9.11 E-03	57697
Nickel	10.7	1.17 E-03	7399
Gold	5.7	6.25 E-04	3961
Subtotal		1.09 E-02	69057

Metal Lid			
Item	% of Metal Lid	Weight (g)	PPM
Iron	58.0	1.46 E-02	92621
Nickel	42.0	1.06 E-02	67098
Subtotal		2.52 E-02	159718

Solder Seal			
Item	% of Solder	Weight (g)	PPM
Pb	91.1	2.01 E-03	12703
Sn	6.3	1.39 E-04	882
Silver	1.3	2.79 E-05	177
Indium	1.3	2.77 E-05	176
Subtotal		2.20 E-03	13938

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Al	99.0	3.00 E-05	190
Si	1.0	3.00 E-07	2
Subtotal		3.03 E-05	192

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	6.00 E-03	38013

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Polyimide	94.5	6.90 E-03	43706
Silicon dioxide	5.5	4.02 E-04	2544
Subtotal		7.30 E-03	46249

Package Totals	
Weight (g)	PPM
1.58 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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